





Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT - PCN #: F-0203-04

**PCN Type:** To implement auto mold process

**Data Sheet Change:** N/A

**Detail of Change:** The auto mold proces is being implemented to improve the product manufacturability by reducing the process cycle time. This change will have the following impact on the package dimension:

DESCRIPTION	FROM	TO
Mold Cap Thickness	1.17 mm	0.80 mm
Package Thickness	2.13 mm	1.81 mm

### Conversion schedule (Estimated)

Sample Availability

Production Shipments

BG121

Availble

5/3/2002

Please contact your local field sales representative for sample availability and production shipments.



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Qualification Plan: P01-03-06

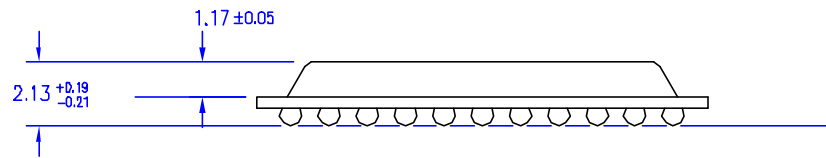
Expected Completion Date: 4/26/2002

Test Vehicle: 72825LB15BG

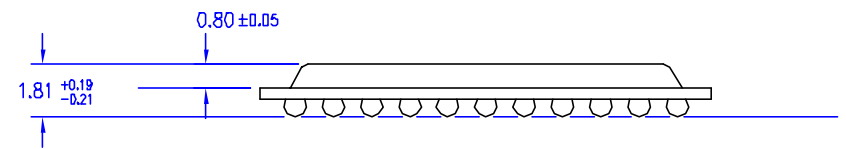
Test Description Condition	Test Methods	Sample Size / # Fails	Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @ 130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883 Method 1010	45/0	
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	
Package Moisture Characterization	JEDEC J-STD-20	22/0	
Internal Visual Inspection	MIL-STD-883 Method 2010	5/0	
External Visual Inspection	MIL-STD-883 Method 2009	25/0	
S.A.T	JEDEC J-STD-35	10/0	
X-ray Examination	Per IDT specification	45/0	
Bond Pull Test	MIL-STD-883 Method 2011	5/0	
Bake & Ball Shear Test	EIA/JESD22-B116	5/0	
Physical Dimension	MIL-STD-883 Method 2016	5/0	
Solder Ball Shear	JESD22-B117	3/0	
Resistance to Solvents	MIL-STD-883 Method 2015	5/0	

# BG121

FROM:



TO:



ALL DIMENSIONS IN MM